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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Applicant:	§	Art Unit:	2814
Ilya Karpov et al.	§		
	§	Examiner:	Long Pham
Serial No.:	§		
10/822,361	§	Docket:	ITL.0835D1US
	§		P14730D
Filed:	§		
April 12, 2004	§	Assignee:	Intel Corporation
	§		
For:	§	Conf. No.	3077
Fabricating Deeper and			
Shallower Trenches in			
Semiconductor Structures			

Mail Stop **Amendment**
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

REPLY TO OFFICE ACTION

Sir:

In response to the office action mailed November 15, 2007, please amend the above-referenced patent application as follows:

Date of Deposit: January 7, 2008
I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as **first class mail** with sufficient postage on the date indicated above and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.
Cynthia L. Hayden
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